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# Phase Change Memory: Mainstream Ambitions

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## Report Offerings

### ***How 3D Memory Stacks Up***

Compares the technology, challenges and cost of various 3D memory options including stacked charge trapping technologies from Samsung and Toshiba, and cross-point RRAM arrays.

### ***NAND Quarterly Insights***

A quarterly supply-demand forecast published four times a year which includes vendor shipments, wafer capacity, capex, and application forecasts. The report also contains roadmaps and costs for SLC, MLC, 3-bit/cell and 4-bit/cell technologies.

### ***Applications for 3-bit per cell/4-bit per cell NAND Flash Memories***

An in-depth analysis of the technology, performance, cost, market and applications for 3-bit per cell and 4-bit per cell NAND flash memories.

### ***Key NAND Flash Memory Design Intellectual Property***

Technical innovations, particularly in NAND flash memory design are key enablers of multi-level cell NAND flash memories, especially 3-bit per cell and 4-bit per cell technologies. This report identifies important intellectual property related to sensing architectures, source voltage noise compensation, programming algorithms, disturbs reduction, temperature compensation, high voltage switch, coding schemes and error correction codes from Hynix, Micron, Samsung, SanDisk, STMicroelectronics and Toshiba.

### ***Read Architectures for Multi-bit per cell NAND Flash Memories***

Compares the technical merits of the All Bitline sensing architecture vs. conventional voltage sensing scheme in NAND flash memories.

### ***SSD Insights***

Provides an overview of the technology, performance, cost trends and market and application forecasts of solid state drives in computing applications.

### ***ECC and Signal Processing Technology for Solid State Drives and Multi-bit per cell Flash Memories***

Explores the various ECC techniques used in NAND flash memories including BCH, RS as well as emerging DSP coding techniques. DSP coding techniques will be essential for implementing 3-bit and 4-bit per cell NAND flash memories and future generations of NAND flash in solid state drives.

### ***Comparison of 3-bit per cell NAND Flash Memories***

This report compares the 3-bit per cell NAND flash memory implementations of SanDisk/Toshiba, Hynix and Samsung and discusses the advantages and disadvantages of each.

### ***SSD Innovations***

Explores innovative technologies for improving the performance, endurance and reliability of solid state drives.

### ***Graphics DRAM***

Examines the competitive landscape for graphics DRAM as well as market and technology trends.